

Title (en)

ADHESIVE COMPOSITIONS, BONDING FILMS MADE THEREFROM AND PROCESSES FOR MAKING BONDING FILMS

Title (fr)

COMPOSITIONS ADHESIVES, FILMS DE LIAISON DERIVES ET PROCEDES DE FABRICATION DE FILMS DE LIAISON

Publication

EP 0833874 A1 19980408 (EN)

Application

EP 96918301 A 19960605

Priority

- US 9609412 W 19960605
- US 49326395 A 19950621

Abstract (en)

[origin: WO9700923A1] A photostable adhesive composition comprises: a) an aromatic polyepoxide; b) a heat activated curative for polyepoxide; c) a thermoplastic polymer; d) a polyfunction (meth)acrylate; and e) optionally, a bireactive compound that contains at least one (meth)acrylate group and at least one group that is reactive with aromatic polyepoxide. The adhesive compositions can be used to prepare adhesive bonding films in a process that uses electron beam irradiation.

IPC 1-7

C09J 4/02; **C09J 163/00**; **C09J 7/00**

IPC 8 full level

C09J 4/06 (2006.01); **C08F 283/10** (2006.01); **C08G 59/50** (2006.01); **C08G 59/70** (2006.01); **C09J 4/02** (2006.01); **C09J 163/00** (2006.01); **H05K 3/38** (2006.01)

CPC (source: EP KR)

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Citation (search report)

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